

# **SOD-123FL Plastic-Encapsulate Diodes**

## HALOGEN FREE

#### **Transient Voltage Suppressor Diodes**

#### **Features**

P<sub>PPM</sub> 200WV<sub>RWM</sub> 3.3V

•Low power loss, high efficiency

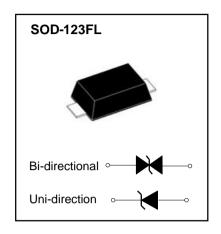
Excellent clamping capability

## **Applications**

- Protect sensitive circuit from damage by high voltage transients
- Lighting, ESD transient voltage protection of IC, system
- Inductive switching load protection of IC, system
- Electrical Fast Transient Immunity protection of IC, system

#### **Mechical Data**

- Case: SOD-123FL molded plastic
- Molding compound: UL flammability classification rating 94V-0
- Terminals: Solder plated, solderable per MIL- STD-202, Method 208
- Polarity: Color band denotes cathode end



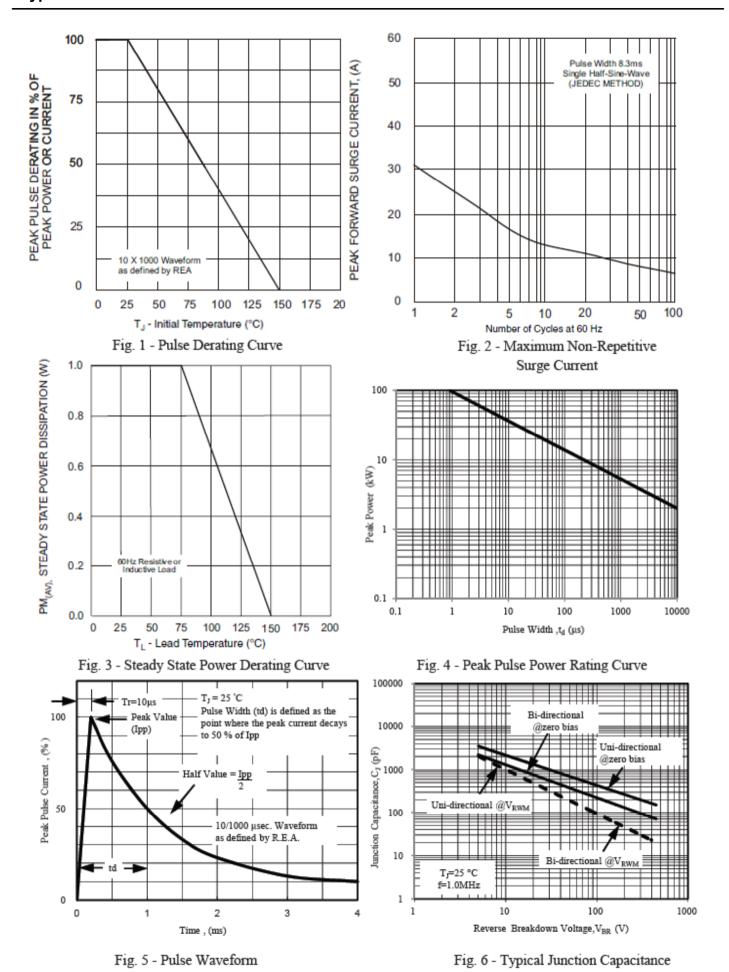
## **Limiting Values (Absolute Maximum Rating)**

Item	Symbol	Unit	Conditions	Max
Peak power dissipation	P <sub>PPM</sub>	w	with a 10/1000us waveform <sup>(1)</sup>	200
Peak pulse current	I <sub>PPM</sub>	Α	with a 10/1000us waveform	See Next Table
Surge(Non-repetitive)Forward Current	I <sub>FSM</sub>	Α	Peak forward surge current, 8.3 ms single half sinewave unidirectional only	30
Peak Forward Voltage	V <sub>F</sub>	V	Maximum instantaneous forward voltage at 10 A for unidirectional only	3.5
Operating junction and storage temperature range	T <sub>J</sub> ,T <sub>STG</sub>	$^{\circ}$ C		-55 to +150
	R <sub>eJL</sub>	°C/W	Between junction and lead	26
Thermal resistance	R <sub>0JA</sub>	°C/W	Between junction and Ambient	300
	R <sub>θJC</sub>	°C/W	Between junction and Case	40

1)Non-repetitive current pulse per Fig.5 and derated above TA= 25 °C per Fig.1;

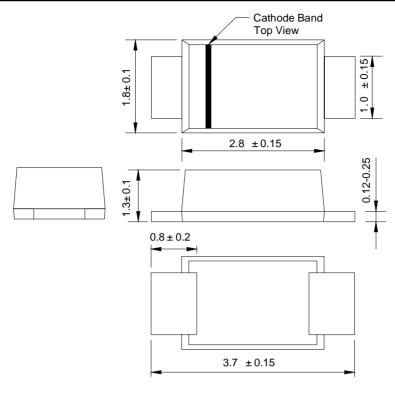
Part N	umber	Mar	vice king ode	Reverse Stand-off Voltage	Vol	kdown tage @ I <sub>T</sub>	Test Current	Max. Clamping Voltage @ I <sub>PP</sub>	Max. Peak Pulse Current	Max. Reverse Leakage @ V <sub>RWM</sub>
UNI-POLAR	BI-POLAR	UNI	BI	$V_{RWM}(V)$	Min.(V)	Max.(V)	I <sub>T</sub> (mA)	V <sub>C MAX.</sub> (V)	$I_{PP}(A)$	I <sub>R</sub> (uA)
SMF3V3A	SMF3V3CA	3V3	3V3C	3.30	4.10	5.10	10	7.3	27.5	1000

## Typical Characteristics



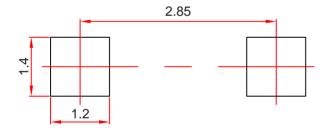
HIGH DIODE SEMICONDUCTOR

## **SOD-123FL** Package Outline Dimensions



Dimensions in millimeters

## SOD-123FL Suggested Pad Layout



#### Note:

- 1. Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

# **Ordering Information**

Part Number	Package	Shipping Quantity
SMF3V3(C)A	SOD-123FL	3000/tape&Reel

## **Marking Diagram**



Bi-directional



# Reel Taping Specifications For Surface Mount Devices-SOD-123FL

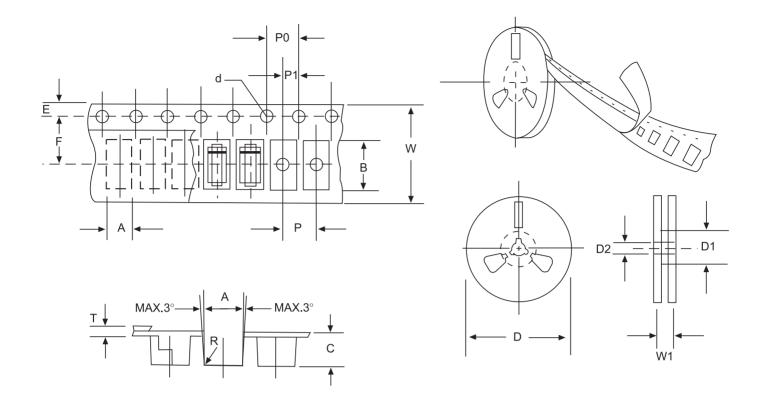


FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SOD-123FLmm(inch)
Carrier width	A	2.05±0.1(0.081±0.004)
Carrier length	В	3.95±0.1(0.156±0.004)
Carrier depth	С	1.45±0.1(0.057±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	178±2.0(7.0±0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	3.50±0.1(0.138±0.002)
Punch hole pitch	Р	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	Т	0.21±0.25(0.008±0.010)
Tape width	W	8.0±0.2(0.315±0.008)
Reel width	W1	10.0±2.0(0.394±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.